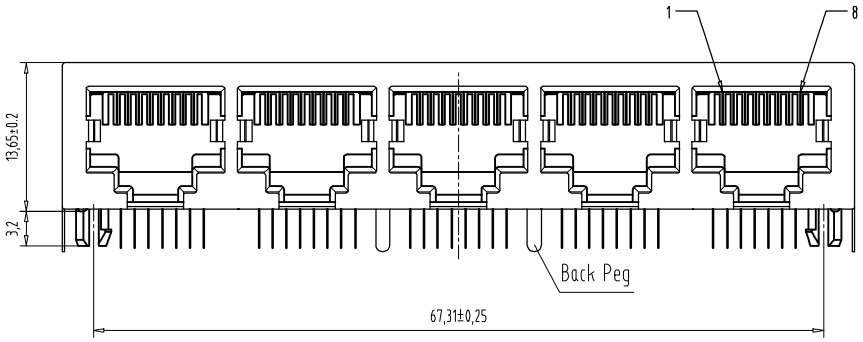
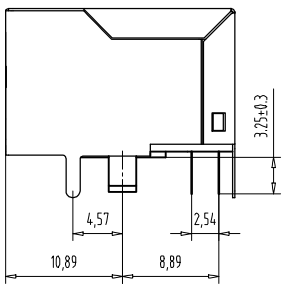
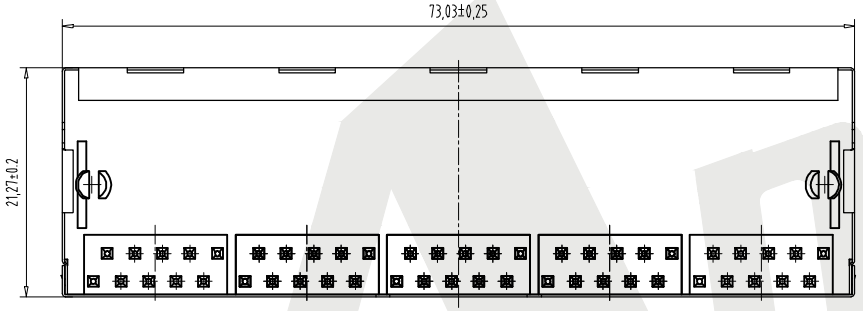
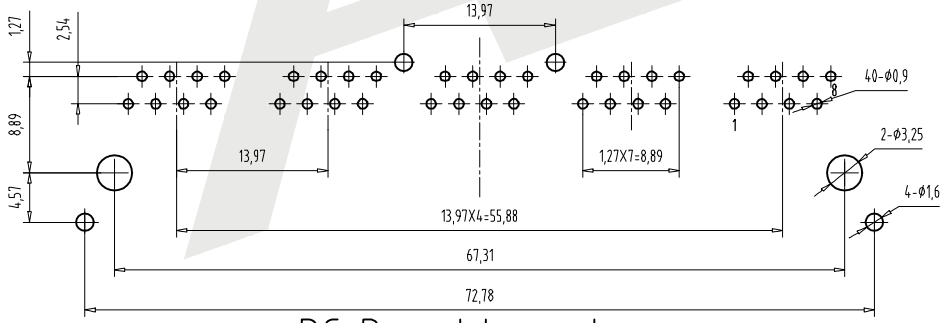
HSF Pb RoHS




PC Board Layout
Component Side Shown

NOTES:
MATERIAL:
1. HOUSING MATERIAL:GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL:PHOSPHOR BRONZE t=0.3mm
3. PLATING:SELECTING GOLD PLATING 1μ~50μ"OVER NICKEL IN CONTACT AREA.150μ" TIN PLATIN.OVER NICKEL IN SOLDER AREA
4. SHIELD:0.2mmTHICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL
1. VOLTAGE RATING:125V AC RMS
2. CURRENT RATING:1.5AMP
3. CONTACT RESISTANCE:30 MILLIOHMS MAX
4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL
1. DURRABILITY:750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER:1 LB MIN

REVIRONMENTAL
1. STORAGE:-40° C TO 85° C
2. OPERATION:0° C TO 70° C

## Order code:

ATRJ5921 - 8P - 8C - X - D - D - C

① ② ③ ④ ⑤ ⑥ ⑦

① SERIES NO:
② NUMBER OF POSITIONS(10P,8P,6P,4P)
③ NUMBER OF CONTACTS(10C,8C,6C,4C)
④ Contact Plating
G0:GOld flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
SN:Tin
⑤ Shield
A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml
⑥ Ports
A:1X1P
B:1X2P
C:1X4P
D:1X5P
E:1X6P
F:1X8P
⑦ PCB layout style:
A:TYPE 1 front legs 3.05
B:TYPE 1 front legs 3.68
C:TYPE 1 front legs 4.57
D:TYPE 2 Back legs 3.05
E:TYPE 2 Back legs 3.68
F:TYPE 2 Back legs 4.57

| REV | DESCRIPTION | DATE |
|---|---|---|
| | | |
| | | |
| | | |

Unless Otherwise specified tolerance
X. ±0.35 X.XX:±0.20
X.X:±0.25 X.XXX:±0.15

| | |
|---|---|
| SCALE: As Shown | UNIT: mm |
| DRAW Wu Feng Rong | DATE 22/03/2018 |
| CHECK BobYang | DATE 22/03/2018 |

3rd ANGLE PROJECTION


ANTENK ELECTRONICS CO,.LTD
Http://www.antenk.com
E-mail:sales@antenk.com


TITLE: RJ45 Jack side entry, Shielded, 1X5P Front 4.57

DRAWING NO: ATRJ5921-8P8C-X-D-D-C

PRODUCT NO: ATRJ5921-8P8C-X-D-D-C